
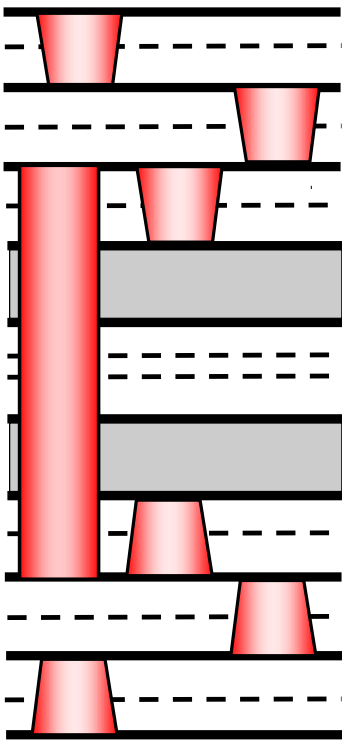


Build Up HDI (Standard)											
HDI10_3+4(6b)+3_1,50_35_engl		10 - Layers									
		Core: 0,36 mm Cu 35/35 µm									
WE-Articel No.:		3 + 4(6B) + 3									
Customer:											
layer description		configuration			Raw-Material	CU	PREPREG	Final Thickness	Customer requirements		
Customer	WE							[µm]	[µm]		
	TOP/VS				Foil	12 µm	1)	12			
							1 x 1080	60			
	2				Foil	12 µm		30			
							1 x 1080	60			
	3				Foil	9 µm		30			
							1 x 1080	60			
	4							35 µm		33	
					0,360 mm					360	
	5							35 µm		33	
						2 x 1080	124				
	6				35 µm		33				
		0,360 mm					360				
	7				35 µm		33				
						1 x 1080	60				
	8	Foil	9 µm		30						
						1 x 1080	60				
	9	Foil	12 µm		30						
						1 x 1080	60				
	BOT/RS	Foil	12 µm	1)	12						
					1) copper thickness outer layers: appr. 55 µm						
					total material thickness: 1480						
					Note: Lamination thickness for Prepregs depending on layout characteristics.						
final lamination thickness:		1,48	+/-	0,13	mm	Date:		Engineer:			
thickness with electro plated Cu:		1,57	+/-	0,16	mm						
total thickness with soldermask		1,63	+/-	0,18	mm						
customer requirement			+/-		mm	point:					
prepared: on 28.03.2006 by S. Keller		checked: on 04.05.2006 by M.Kress			approved: on 04.05.2006 by R.Schönholz			revision 00 page: 21+			